

ABSTRACT OF THE DISCLOSURE

An apparatus for cleaning a mold die set includes a pair of brushes, a pair of vacuum holes, and multiple nozzles. One of the brushes is positioned to scrub a first surface of the mold die set, and the other of the brushes is positioned to scrub a second surface of the mold die set to separate a residue from the first and second surfaces of the mold die set. The vacuum holes receives the separated residue from the first and second surfaces of the mold die set, and through the nozzles, a parting compound is provided to coat the first and second surfaces of the mold die set. The apparatus further includes multiple air holes through which air is blown to the first and second surfaces of the mold die set. An apparatus for semiconductor manufacturing includes a mold die set having a first surface and a second surface and a mold die set cleaner that can remove a residue from the first and second surfaces of the mold die set and coat a parting compound on the first and second surfaces.